Sundance Multiprocessor Technology Limited **Design Specification**

Form: QCF51 Dated: 20 June 2003

Revision: 6

Unit / Module Name:	General Dynamics data acquisition and processing system
Unit / Module Number:	SMT8180
Used On:	
Document Issue:	1.8
Date:	07/02/2005

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Revision History

Issue	Changes Made	Date	Initials
1.0	First release	03/07/03	PV
1.1	Modified: Front panel drawing, Power connections, Ethernet connector	10/07/03	PV
	Added: Box part number, Fans reference, LED hole description, Environment		
1.2	Modified: connectors part numbers and pin out	16/07/03	PV
	Added: connectors mating part		
1.3	Modified: System box figure	17/07/03	PV
	Added: Front panel top view figure		
1.4	Modified: front panel dimensions table	17/07/03	PV
1.5	Modified: front panel dimensions table	18/07/03	PV
1.6	Modified: system box drawing	22/07/03	PV
1.7	Modified: LEMO part number	22/07/03	PV
1.8	Added box drill information	07/02/05	GP

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1 Outline Description

This SMT8180 specification details a system comprising of:

- 2x SMT180
- 9x SMT374
- 2x SMT376
- 1x SMT340
- 1x SMT363V-200
- 1 SHB cable (SMT511)
- 4 MMBX-SMA cable (SMT506-SMA)
- 4 LEMO connectors (2x FAG 2B 314 CLA, FAG 1B 306 CLA, FAG 2B 316.CLA)
- 4 LEMO mating parts (2x PHG 2B 314 CLLD, PHG 1B 306 CLLD, PHG 2B 316 CLLD)
- 1x metal box (Compac, R59012-250-1)

The system offers externally the following features:

- 4x McBSP connections
- 2x SMA analogue signals input
- 1x SMA clock input
- 1x SMA trigger input
- 1x Ethernet connection

1.1 Related Documents

SMT180 Technical specifications

2 Mechanical configuration

2.1 Box

The electronics system fits in a metal box that offers a very good shield against electromagnetic interferences. Two SMT180 cards carry all the TIM modules necessary to the required operations. The first SMT180 is mounted at the bottom of the box and will be kept in place by screws through the mounting holes. The second SMT180 will be mounted on the lead of the box and screwed the same way as the first one. The TIM sites for both carriers will face the inside of the box, thus guaranteeing optimal heat dissipation during processing thanks to the 8 fans blowing air in and out. The fans can be fitted outside and/or inside the box. The Sunon fans (provided by GD) will be on the outside, the ACT-RX fans (BP0535SA7) on the inside.

The box dimensions are as follow:

Length: 12.5" = 318mmWidth: 10" = 254mmHeight: 2.5" = 64mm

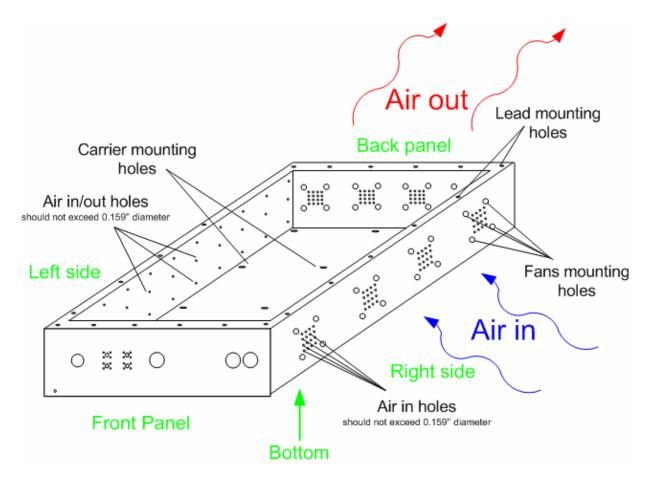
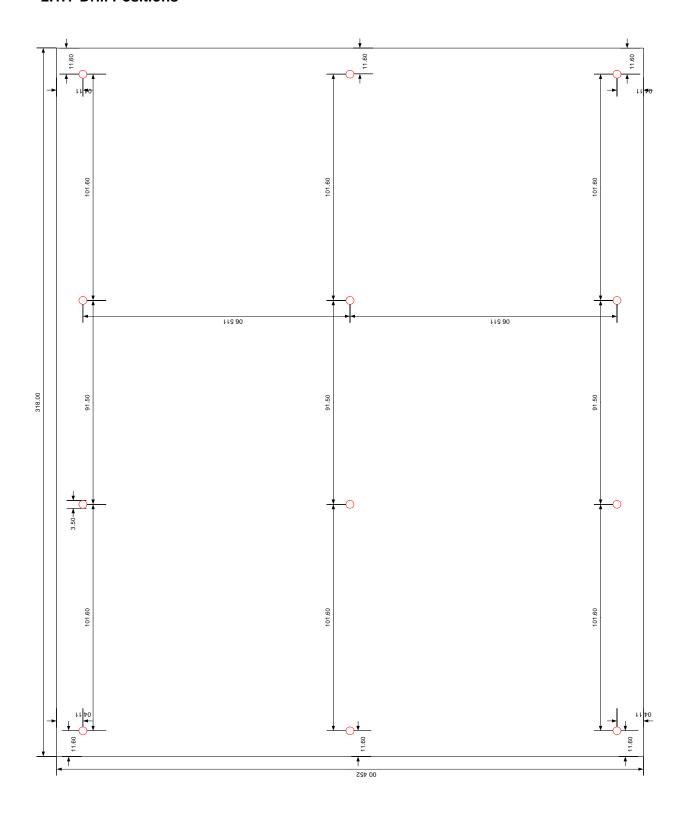


Figure 1 : System box

2.1.1 Drill Positions



2.2 Front panel

The different system inputs and outputs are available on the front panel.

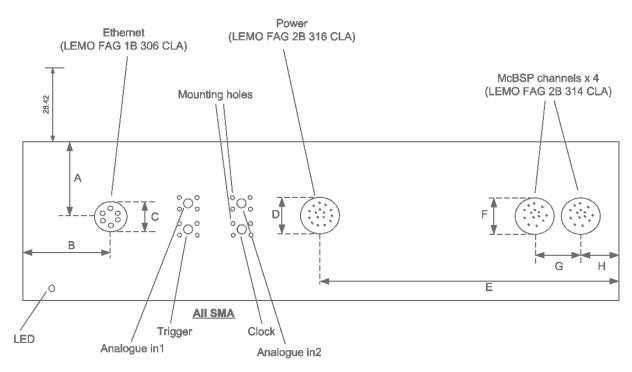


Figure 2 : Front panel

The use of LEMO connectors for McBSP, Ethernet and Power will prevent interferences from entering the box.

The LED hole diameter will not exceed 3mm (0.118"). Light coming out will indicate that the system is powered.

Α	1.25"	31.8mm
В	1.5"	38.1mm
С	0.48"	12.1mm
D	0.59"	15.1mm
Е	3.94"	100mm
F	0.6"	15.2mm
G	0.85"	21.5mm
Η	0.63"	16mm

Dimensions

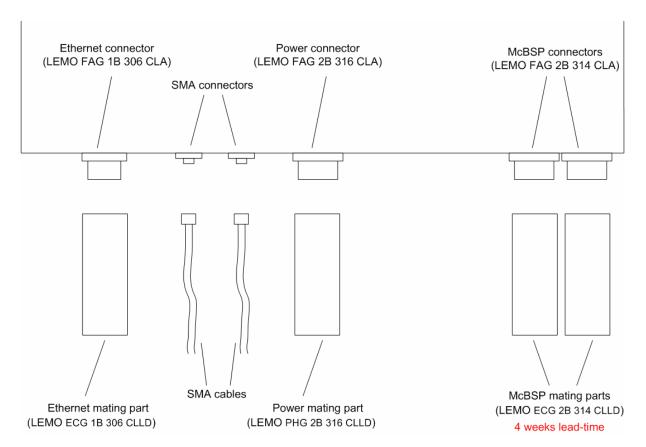


Figure 3: Front panel top view

All the LEMO connectors and mating parts are available except the McBSP mating parts (LEMO PHG 2B 314 CLLD) that are on a four weeks lead-time! However for testing purposes it will be possible to remove the McBSP connectors and have a cable connected to the McBSP channels directly on the TIM modules.

2.3 Connectors pin out

2.3.1 Ethernet

The Ethernet connections from the front panel connector will be wired to the Ethernet connector on the SMT363.

LEMO FAG 1B 306 CLA

TX+	1	TX-	2
RX+	3	RX-	4
NC	5	NC	6

2.3.2 McBSP

There are a total of four McBSP channels available through two LEMO connectors on the front panel. The first McBSP LEMO connector (first McBSP connector from the right on the front panel) will be wired to both McBSP channels on the SMT376 in slot 3 of the SMT180 carrier card 1. The second McBSP LEMO connector will be wired to both McBSP channels on the SMT376 in slot 1 of the SMT180 carrier card 1. The pin out for both connectors is as follow:

LEMO FAG 2B 314 CLA

CLKS0	1	CLKS1	2
CLKR0	3	CLKR1	4
CLKX0	5	CLKX1	6
DR0	7	DR1	8
DX0	9	DX1	10
FSR0	11	FSR1	12
FSX0	13	FSX1	14

2.3.3 **Power**

The Power connections from the front panel connector will be wired to the power connector on both SMT180 carrier cards.

LEMO FAG 2B 316 CLA

1	+5V	2
3	+5V	4
5	GND	6
7	GND	8
9	GND	10
11	+5V	12
13	+12V	14
15	GND	16
	3 5 7 9 11 13	3 +5V 5 GND 7 GND 9 GND 11 +5V 13 +12V

2.4 System outline

The different TIM modules required for data acquisition, processing and interfacing are spread onto two SMT180 carrier boards as follow:

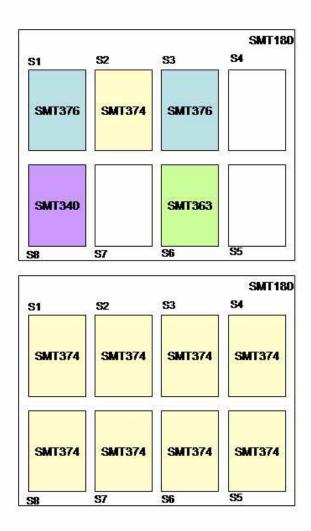


Figure 4: System outline

The TIM modules are connected to each other using ComPort links and SDB cables. The ComPort connections between TIM sites are routed on the SMT180 carrier card. There are also some external ComPorts that enable to connect TIM modules on the first SMT180 to TIM modules on the second SMT180. Please refer the SMT180 specifications for more details.

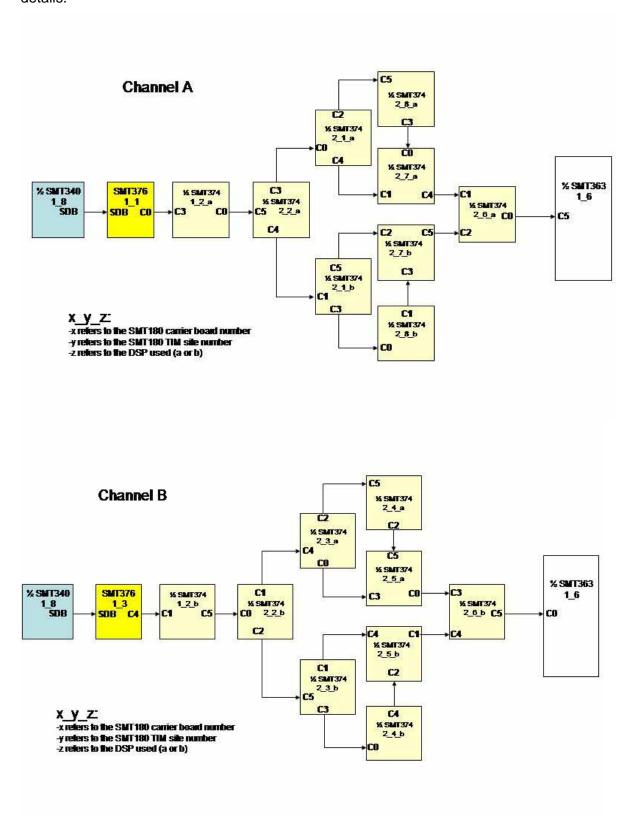


Figure 5: Modules connectivity

3 Power consumption

Power required

+12V	1 A
+5V	14 A

Power distributed

+12V	2 A
+5V	24 A

4 Programmability

The SMT180 carrier card offers an external JTAG connection as well as an external ComPort connection. These can be used in order to debug the system, download a new configuration into the flash or download 3L_diamond applications. Please refer to the SMT180 technical specifications for more information.

5 Environment

The box could be operating in a very demanding environment and some precautions need to be taken.

Electromagnetic interferences could disturb the electronics inside the system. To avoid this problem holes diameter without shielded connectors will not exceed 4mm (0.159").

Fans blow air in and out to cool the system down. It might be necessary to fit some air filters on the fans otherwise the box could become a dust trap.

Screws and connectors inside the box could become loose in the long term because of vibrations; applying some <u>Silastic silicone</u> will prevent this problem from occurring.

6 Safety

This module presents no hazard to the user.